PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Che-Jung Chang	05/08/2006
Chin-Tien Chiu	05/08/2006
Cheeman Yu	05/07/2006
Hem Takiar	05/04/2006
Jack Chang Chien	05/08/2006
Ning Liu	05/08/2006

RECEIVING PARTY DATA

Name:	SanDisk Corporation	
Street Address:	601 McCarthy Boulevard	
City:	Milpitas	
State/Country:	CALIFORNIA	
Postal Code:	95035	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12614945

CORRESPONDENCE DATA

Fax Number: (415)369-9665

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

415-369-9660 Phone:

Email: lmiller@vierramagen.com

Correspondent Name: VIERRA MAGEN/SANDISK CORPORATION

Address Line 1: **575 MARKET STREET**

SUITE 2500 Address Line 2:

Address Line 4: SAN FRANCISCO, CALIFORNIA 94105

ATTORNEY DOCKET NUMBER: SAND-01093US0

REEL: 023490 FRAME: 0967

PATENT

NAME OF SUBMITTER:	Brian I. Marcus
Total Attachments: 7 source=1093-exec_assignment#page1.tif source=1093-exec_assignment#page2.tif source=1093-exec_assignment#page3.tif source=1093-exec_assignment#page4.tif source=1093-exec_assignment#page5.tif source=1093-exec_assignment#page6.tif source=1093-exec_assignment#page7.tif	

PATENT REEL: 023490 FRAME: 0968

JOINT TO CORPORATE ASSIGNMENT

WHEREAS, the undersigned Inventors:

- (1) <u>Che-Jung Chang</u>, a resident of <u>No. 1, Alley 25, Lane 181, SinSheng Rd., Dali city, TaiChung County, 41253, Taiwan, R.O.C.;</u>
- (2) <u>Chin-Tien Chiu</u>, a resident of <u>10F-13</u>, <u>No. 1</u>, <u>Lane 58</u>, <u>Gongye 1st Rd., Situn District</u> #407, <u>Taichung City</u>, <u>Taiwan</u>, R.O.C.;
 - (3) Cheemen Yu, a resident of 2 Dunraven Court, Madison, Wisconsin 53705, U.S.A.;
 - (4) Hem Takiar, a resident of 1544 Blackfoot Drive, Fremont, California 94539, U.S.A.;
- (5) <u>Jack Chang Chien</u>, a resident of <u>9F No.56 Ching-Feng St. Ku-Shan Dist., Kaoshiung City</u> 804, Taiwan, R.O.C.; and
- (6) Ning Liu, a resident of Rm. 602, Bldg. 17, Shuang Long Garden, Long Zhu Rd., Xixiang, Shenzhen, P.R.C.,

have invented certain new and useful improvements in:

METHODS OF PROMOTING ADHESION BETWEEN TRANSFER MOLDED IC PACKAGES AND INJECTION MOLDED PLASTICS FOR CREATING OVER-MOLDED MEMORY CARDS

and have executed a declaration for an application for a United States Patent disclosing and identifying the invention, said application having Application Number 11/373,941 and filed on the 13th day March, 2006.

WHEREAS SanDisk Corporation (hereinafter termed "Assignee"), a corporation of the State of Delaware, having a place of business at 140 Caspian Court, Sunnyvale, State of California, wishes to acquire the entire right, title and interest in and to said application and the invention disclosed therein, and in and to all embodiments of the invention, heretofore conceived, made or discovered jointly or severally by said Inventors (all collectively hereinafter termed "said invention"), and in and to any and all patents, certificates of invention and other forms of protection thereon (hereinafter termed "patents") applied for or granted in the United States and/or other countries.

NOW THEREFORE, for good and valuable consideration acknowledged by each of said Inventors to have been received in full from said Assignee:

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- Said Inventors do hereby sell, assign, transfer and convey to said Assignee, the entire right, title and interest (a) in and to said application and said invention; (b) in and to all rights to apply in any or all countries of the world for patents, certificates of inventions or other governmental grants on said invention, including the right to apply for patents pursuant to the International Convention for the Protection of Industrial Property or pursuant to any other convention, treaty, agreement or understanding; (c) in and to any and all applications filed and any and all patents, certificates of inventions or other governmental grants granted on said invention in the United States or any other country, including each and every application filed and each and every patent granted on any application which is a division, substitution, or continuation of any of said applications; (d) in and to each and every reissue or extension of any of said patents; and (e) in and to each and every patent claim resulting from a reexamination certificate for any and all of said patents.
- Said Inventors hereby jointly and severally covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest herein conveyed in the United States and other countries. Such cooperation by said Inventors shall include prompt production of pertinent facts and documents, giving of testimony, executing of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for complying with any duty of disclosure; (c) for prosecuting any of said applications; (d) for filing and prosecuting substitute, divisional, continuing or additional applications covering said invention; (e) for filing and prosecuting applications for reissue of any of said patents; (f) for interference or other priority proceedings involving said invention; and (g) for legal proceedings involving said invention and any applications therefor and any patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, reexamination proceedings, compulsory licensing proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Inventors in providing such cooperation shall be paid for by said Assignee.
- The terms and covenants of this Assignment shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Inventors, their respective heirs, legal representatives and assigns.
- Said Inventors hereby jointly and severally warrant and represent that they have not 4. entered and will not enter into any assignment, contract, or understanding in conflict herewith.

Date:	(1) Che-lung Chang
	Che-Jung Chang

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Date: 5/8 06	(2)	Chin-Tie	n Chiu
Date		Chin-Tien (Thin

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PATENT REEL: 023490 FRAME: 0971 Date: May 7, 2006 (3) Mulliumen Yu

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Received Time May. 12. 3:19AM

PATENT REEL: 023490 FRAME: 0972 Date: 574/06

Hem Takin

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Date:	5/8/2006	(5)	Tark Chang Chien	,
24.0.		\ /	Jack Chang Chien	

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Date:5/8/2006	(6)Ning Liu
	Ning Liu

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RECORDED: 11/09/2009